

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning at page 8, line 9, with the following rewritten paragraph.

-- The mounting portion 3, on which to mount the semiconductor device 2, is provided at a mid portion of the first insulating substrate 5. The semiconductor device 2 is mounted on the mounting portion 3 using an adhesive, such as a die bond, as later explained. The electrically conductive pattern 4, formed around the mounting portion 3, is made up of a land 21 formed continuously around the rim of one surface of the first insulating substrate 5 and patterns 22 formed towards the mounting portion 3 from the land 21 so as to be electrically connected to a bonding wire 13 as later explained. In the land 21 is formed a plated through-hole 26, which will be explained subsequently. --